KIP-MxM

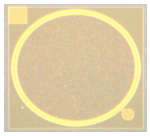
Description

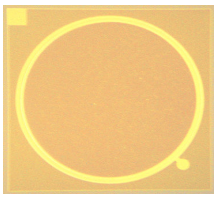
KIP-MxM-1 is InGaAs PIN Photodiode chip with BIG size active diameter(Ø1.0mm,Ø2.0mm,Ø3.0mm).
It is recommended for Laser diode life test and optical power monitoring.

Features

- Front illuminated planar PIN-PD
- High reliability and environmental endurance
- Wide spectral response range from 0.9 um to 1.6 um


KIP-M1M


KIP-M2M


KIP-M3M

Applications

- Laser diode power monitoring
- Laser diode life test

Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Reverse Voltage	$V_{R\ max.}$	10	V
Operating Temperature	T_{opr}	-40 ~ +85	℃
Storage Temperature	$T_{stg.}$	-40 ~ +100	℃
Soldering Temperature *1	$T_{sol.}$	260	℃

**1 : Soldering Time ≤ 10 seconds (At a distance of 1 mm from the package).*

Electro-Optical Characteristics

Parameter		Symbol	Unit	KIP - M1M - 1			KIP - M2M - 1			KIP - M3M - 1			Condition
				Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
Dark Current		I_D	nA		1.0	5.0		2.0	10.0		10.0	50.0	@ V_R=5V, 25℃
Responsivity	1.31um	S	mA/mW	0.85			0.85			0.85			@ V_R=5V, 25℃
	1.55um			0.90			0.90			0.90			
3dB Cut off frequency		f_C	MHz	18	35	-	4	8	-	2	4	-	@V_R=5V, RL=50Ω
Terminal Capacitance		C_T	pF		90	150		250	500		550	1000	@ V_R=5V, f=1MHz

* These specifications are subject to change without notice.

Physical Dimension Properties

Parameter	Symbol	KIP - M1M - 1	KIP - M2M - 1	KIP - M3M - 1	Unit
		Typ.	Typ.	Typ.	
Active area	Ø	1.0	2.0	3.0	㎜
Chip out dimension	Sq	1.4 x 1.4	2.4 x 2.4	3.6 x 3.6	㎟
bonding Pad Size	Ø	100			㎛
Chip Thickness	t	150			㎛

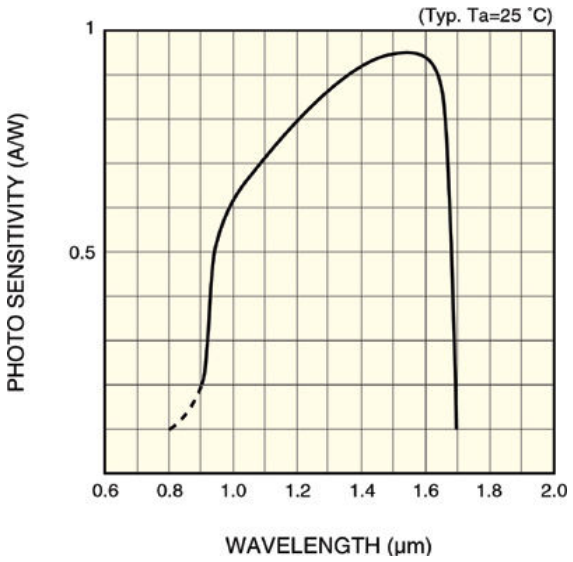
Ordering information

KIP	Data Rate	Active area	Carrier type
KODENSHI InGaAs PIN Photodiode Chip	M: Monitoring	1M: Ø1.0 ㎜	1: chips in gel pack
		2M: Ø2.0 ㎜	
		3M: Ø3.0 ㎜	2: chips on submounter
			3: chips on blue tape

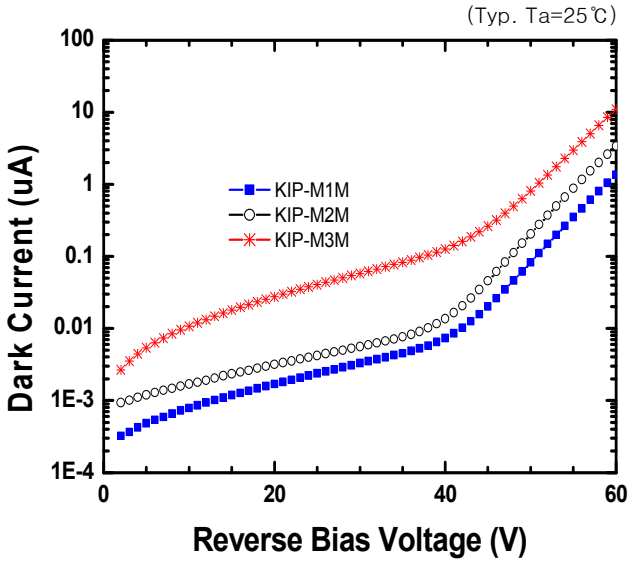
The engineering spec can be revised without any previous notice.
When customer's applying, please request us a revised specification before submitting the specification to the customers.

KIP-MxM

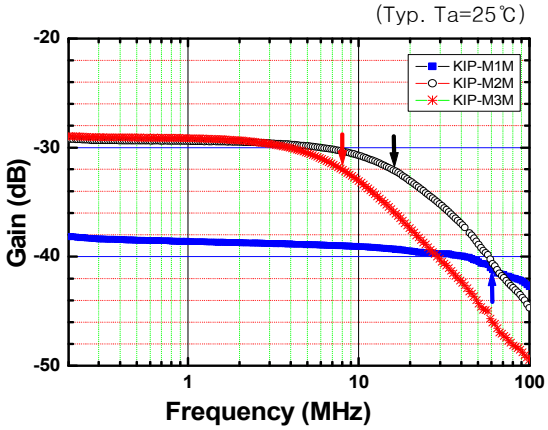
■ Spectral response range



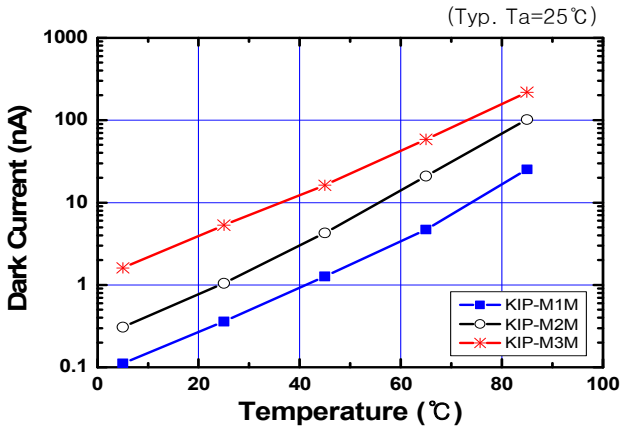
■ Dark current vs Reverse voltage



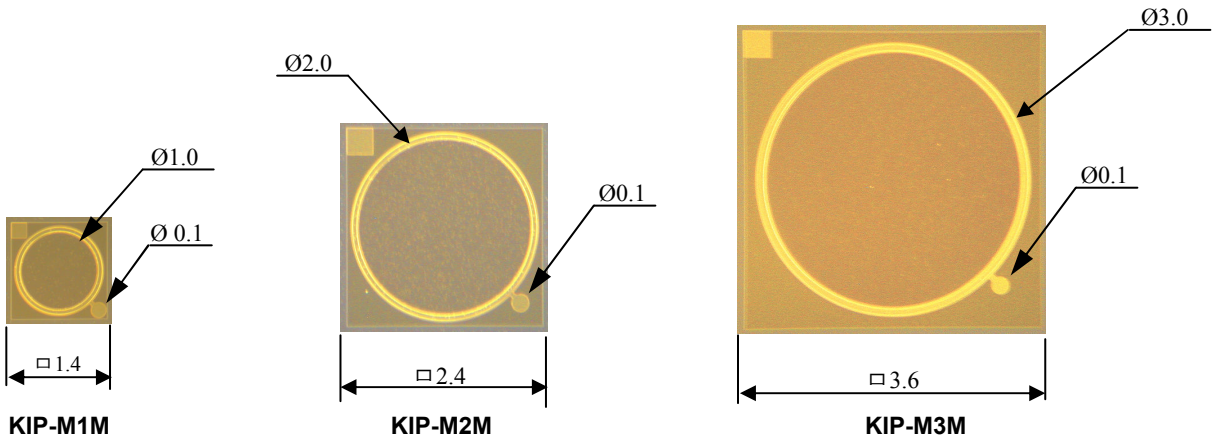
■ -3dB Cutoff Frequency



■ Dark Current vs Operating Temperature



■ Chip out dimension (unit:mm)



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